

- **SAW Filter for Cable System**
- **Complies with Directive 2002/95/EC (RoHS)**

Characteristics:

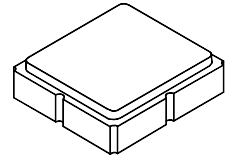
Balanced-to-balanced operation

Terminating source/load impedance : $Z_S = 200 \Omega$



SF2081E

**1220 MHz
SAW Filter**



SM3030-8

Maximum Rating

Rating	Value	Units
Input Power Level	0	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			1220		MHz
Insertion Loss, 1195 to 1245 MHz	IL			3.0	4.0	dB
3 dB Bandwidth	BW ₃		50	56		MHz
Amplitude Ripple, 1200 to 1240 MHz, -30 to +45 °C				2.0	2.2	dB
Attenuation Referenced to Minimum Insertion Loss:						
$F < f_C - 48 \text{ MHz}$			35	44		dB
$F > f_C + 48 \text{ MHz}$			30	40		
Group Delay Ripple				35	100	nSP-P

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	840, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

	Connection	Terminals
Port 1	Balanced Input	1,2
Port 2	Balanced Output	5,6
	Ground	All Others

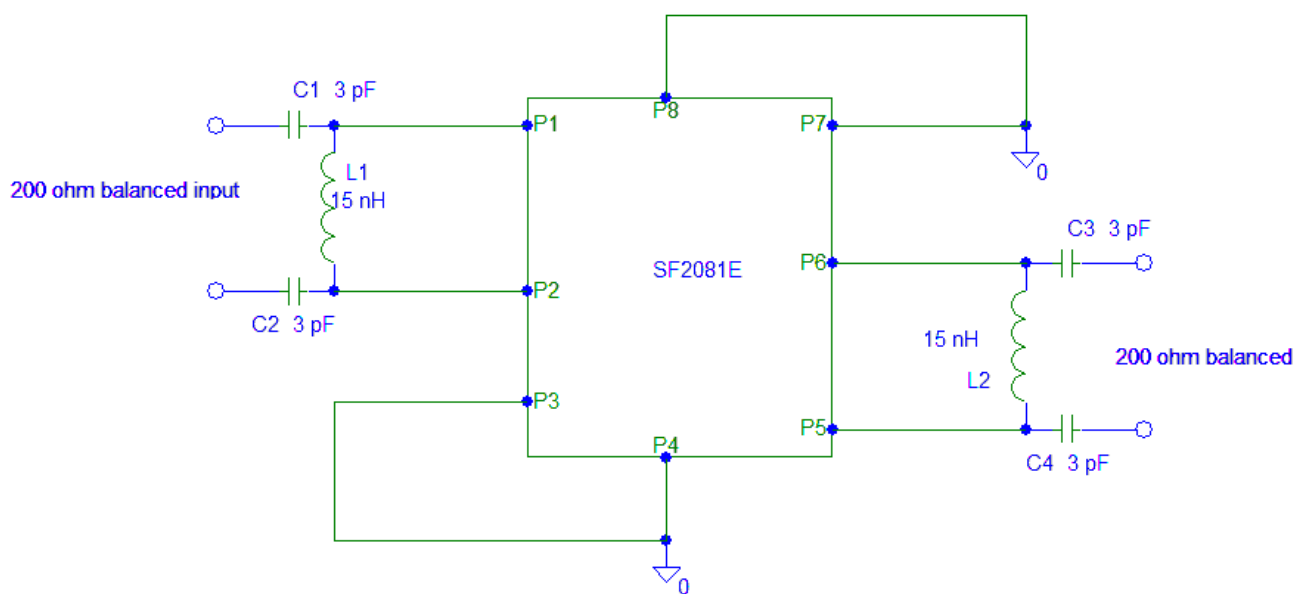
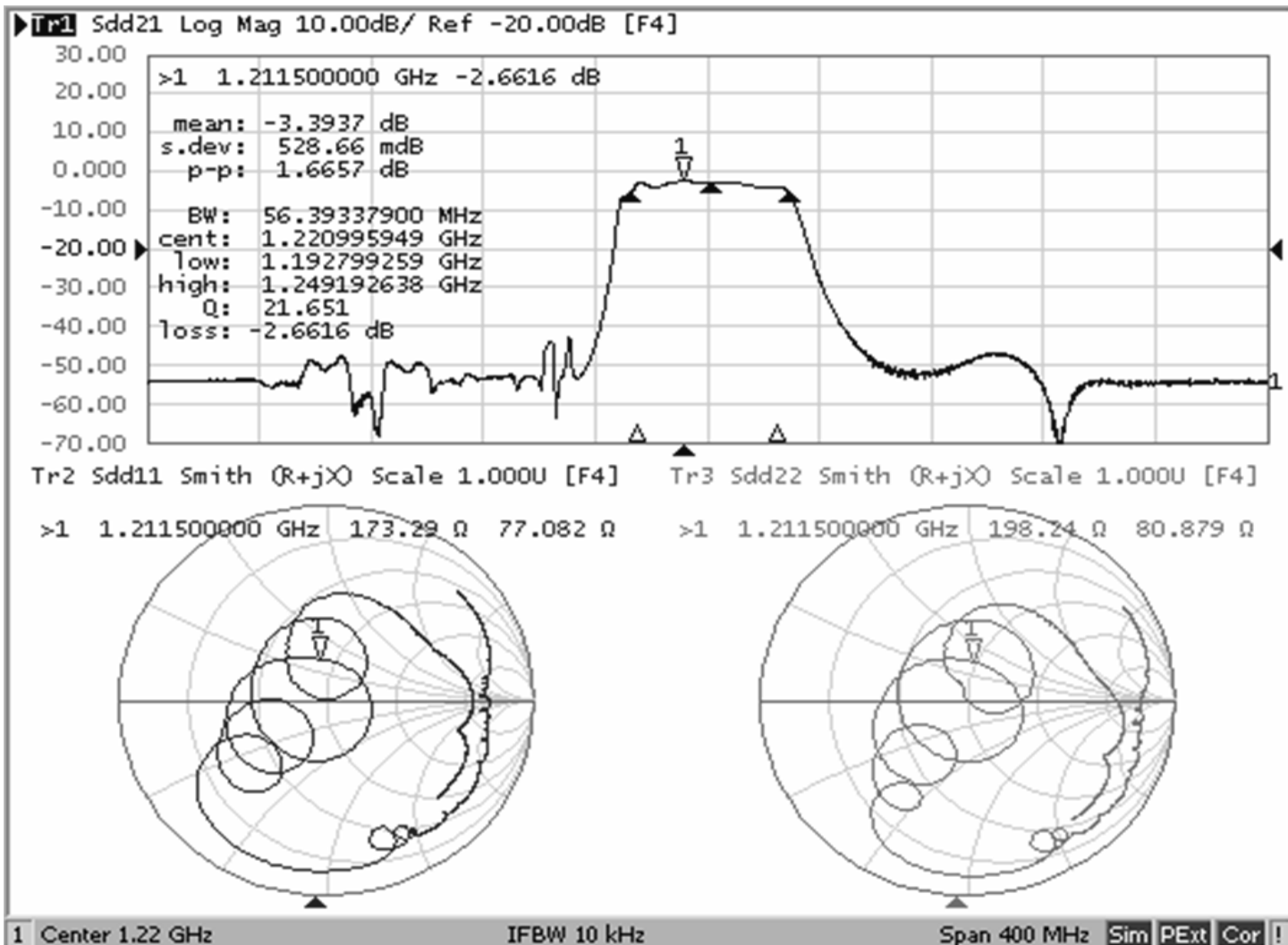
Dot Indicates Pin 1



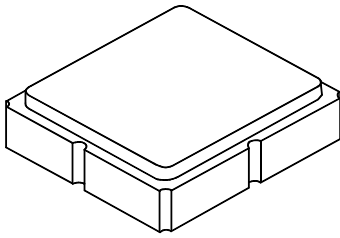
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. US and international patents may apply.
2. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.
3. Electrostatic Sensitive Device. Observe precautions for handling.

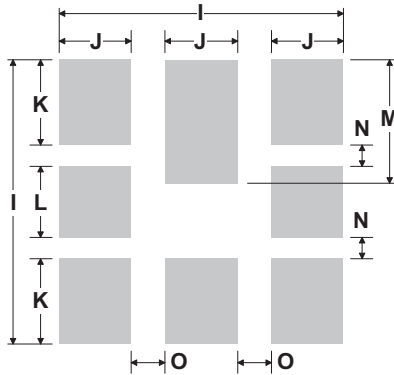


8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

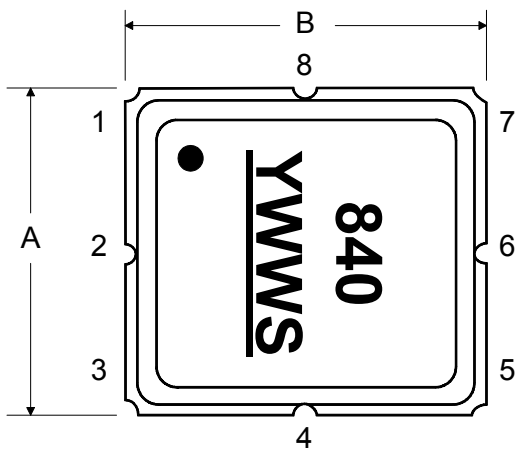


PCB Footprint Top View

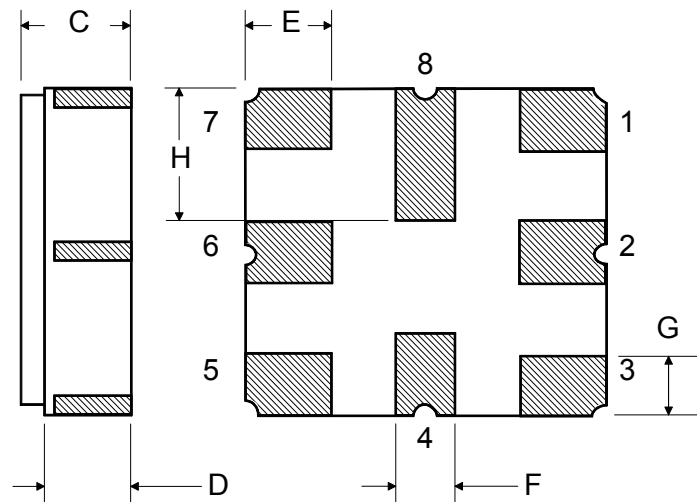
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
	Pb Free

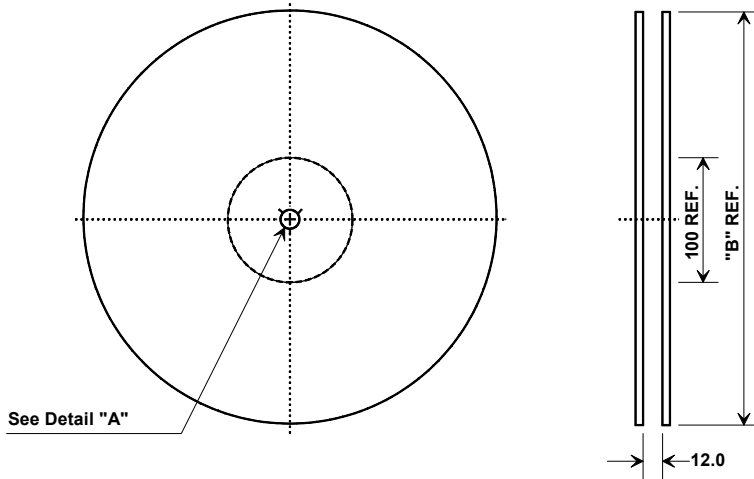
TOP VIEW



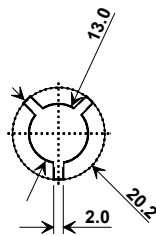
BOTTOM VIEW



Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.4 mm
Pitch	8.0 mm
W	12.0 mm

COMPONENT ORIENTATION and DIMENSIONS

